

GaN GROWTH ON β -Ga₂O₃ SUBSTRATES BY HVPE

V.I. Nikolaev^{1,2,3}, A.I. Pechnikov³, V.N. Maslov^{1,2}, A.A. Golovatenko^{1,2,3},

V.M. Krymov^{1,2}, S.I. Stepanov^{1,4}, N.K. Zhumashev¹, V.E. Bougrov¹, A.E. Romanov^{1,2}

¹ITMO University, Kronverkskiy propect 49- A, St. Petersburg, 197101, Russia

²Ioffe Physical-Technical Institute, Polytechnicheskaya st. 26, St. Petersburg, 194021, Russia

³Perfect crystals LLC, Polytechnicheskaya st.,28; St. Petersburg, 194064, Russia

⁴St. Petersburg Polytechnic University, Polytechnicheskaya st. 29, St. Petersburg, 195251, Russia

*e-mail: vladimir.i.nikolaev@gmail.com

Abstract. Gallium oxide β -Ga₂O₃ crystals were grown by a seedless crystallization from a Ga₂O₃-Al₂O₃ melt. Platelets with (100) orientation were produced by cleaving of the β -Ga₂O₃ ingot. These platelets were employed as substrates for GaN deposition by HVPE. Properties of the β -Ga₂O₃ crystals and GaN epitaxial layers on β -Ga₂O₃ substrates were studied.

1. Introduction

Gallium oxide (β -Ga₂O₃) is a promising wide-band-gap semiconductor material for applications in optoelectronics and power semiconductor technology. The band gap energy of β -Ga₂O₃ is about 4.8-4.9 eV which is the largest value amongst other semiconducting oxides. Because of the extremely wide band gap, the material is transparent from the visible to the UV-C (260 nm) range of the spectrum. Gallium oxide is essentially insulating, however it can also exhibit n-type conductivity when synthesized under reducing conditions. Such unintentional conductivity is commonly attributed to oxygen vacancies [1] or hydrogen shallow donors [2]. Also, n-type β -Ga₂O₃ can be produced by doping with silicon [3] and tin [4, 5].

High quality single crystals of β -Ga₂O₃ can be grown from melt by Czochralski [6, 7], edge-defined film-fed growth (EFG) [5] and floating zone (FZ) [8] methods. This is an important advantage of β -Ga₂O₃ over conventional wide bandgap semiconductors such as gallium nitride and silicon carbide which are mainly produced by crystallization from the gas phase. When compared to other methods, melt growth techniques offer the benefits of lower energy consumption, higher throughput and superior material quality. In the case of mass production, the price of β -Ga₂O₃ substrates is expected to be significantly lower than those for GaN and SiC substrates.

Various semiconductor devices made of β -Ga₂O₃ have been reported, for example, UV photodetectors [9] and field effect transistors [10, 11]. Another promising application of β -Ga₂O₃ is its use as a substrate for epitaxial growth of GaN and related III-nitrides. Ultimately, native GaN substrate would be the best choice for III-nitride devices as only homoepitaxial growth can provide the lowest defect density, zero lattice mismatch and no thermal coefficient difference. However, the cost of bulk GaN remains prohibitively high for the majority of device applications. So far, the use of GaN substrates is economically viable only in niche applications such as manufacturing of violet laser diodes for blu-ray DVD drives. Sapphire is generally used as a substrate material for GaN growth. Although the technology of GaN on sapphire is well established and mature, it has fundamental limitations such as poor lattice

match (13.9 %) and insulating nature of sapphire. By contrast, the lattice mismatch between β -Ga₂O₃ and GaN is significantly lower. For GaN films grown on *a* plane β -Ga₂O₃ the epitaxial relationship is (011) β -Ga₂O₃ || (10 $\bar{1}$ 0) GaN and the lattice mismatch is only 2.6 % [12]. Muhammed *et al* [13] reported on GaN growth on ($\bar{2}$ 01) β -Ga₂O₃ substrates. In this case the epitaxial relationship is (010) β -Ga₂O₃ || (11 $\bar{2}$ 0) GaN leading to a lattice mismatch of 4.7 %. N-type β -Ga₂O₃ is a reasonable conductor which makes it possible to produce devices with a vertical geometry. Several other research groups also published results on GaN growth on β -Ga₂O₃ substrates using various methods [14–17]. The growth of GaN-based light emitting diode structures on β -Ga₂O₃ substrates has been demonstrated by Zi-Li *et al.* [18].

Earlier, we reported on the feasibility of growing β -Ga₂O₃ crystals in non-metallic crucibles [19], and it was demonstrated that the most suitable crucible material is sapphire, Al₂O₃. Sapphire does not chemically interact with the Ga₂O₃ melt, however dissolution of the crucible walls was observed. Consequently, the produced ingot was an alloy of Ga₂O₃ and Al₂O₃. More detailed study of crystal growth in the Ga₂O₃-Al₂O₃ system can be found in [20].

In this work we present our initial results on GaN epitaxial growth on β -Ga₂O₃ substrates by hydride vapour phase epitaxy (HVPE).

2. Experiment

β -Ga₂O₃ crystals were grown in a growth chamber equipped with a graphite resistive heater. Gallium oxide powder (99.5 %) was used as a starting substance. The diameter of sapphire crucible was 25 mm and the wall thickness was about 3 mm. Ga₂O₃ charge was loaded into the crucible, heated up to 1850 °C and soaked at this temperature for 30-60 minutes in order to homogenize the melt. The growth chamber was filled with argon to a pressure of 0.5 bar. The melt was cooled to room temperature during 5 hours. Ga₂O₃ crystals were formed by free crystallization of the melt. The produced ingot was cleaved into platelets having (100) orientation. Cleaved single crystals have been studied by X-ray, optical and scanning electron microscopy.

GaN deposition on β -Ga₂O₃ platelets was performed in a home-made horizontal hot wall HVPE reactor. High-purity metallic gallium (Ga) (99.9999 %) and gaseous ammonia (NH₃) (99.9995 %) were used as gallium and nitrogen precursors, respectively. Hydrogen chloride (HCl) gas was passed over Ga at 600°C to form GaCl vapour, which was transported to the growth zone of the reactor and reacted with NH₃ at 1050 °C to produce GaN. Argon (Ar) was used as a carrier gas. The growth was performed at atmospheric pressure. Typical growth rates were in the range from 30 to 100 μ m/h.

3. Results and discussion

The structure and properties of β -Ga₂O₃ crystals. The produced β -Ga₂O₃ ingots were aggregates composed of several single crystals of various size. Some crystals measure over 10 mm across but because of high fragility of crystals along cleavage planes it was extremely difficult to separate larger plates. The maximal size of the successfully separated single crystal was about 8 mm across. As confirmed by electron microprobe analysis, crystals contained up to 10 at.% of aluminium because the sapphire crucible was partially dissolved by the Ga₂O₃ melt.

Some of the single crystals (Fig. 1) were of good optical quality, colourless and transparent. The transmission spectrum measured using Specord UV-VIS spectrophotometer shows an absorption edge at wavelength around 260 nm (Fig. 2). The X-ray diffraction spectrum confirms that the obtained β -Ga₂O₃ single crystals are of good structural quality. The ω -scan rocking curve had a half width at half maximum of about 70 arcsec.

The smallest lattice mismatch (2.6 %) of β -Ga₂O₃ to GaN is achieved for (100) oriented

substrates. This orientation is particularly interesting for substrate preparation because (100) is the strongest cleavage plane (100) in β -Ga₂O₃. Therefore thin platelets of (100) orientation can be relatively easy produced by cleaving. Another advantage is that as-cleaved surface is already smooth and does not require any additional grinding or polishing before epitaxial growth.

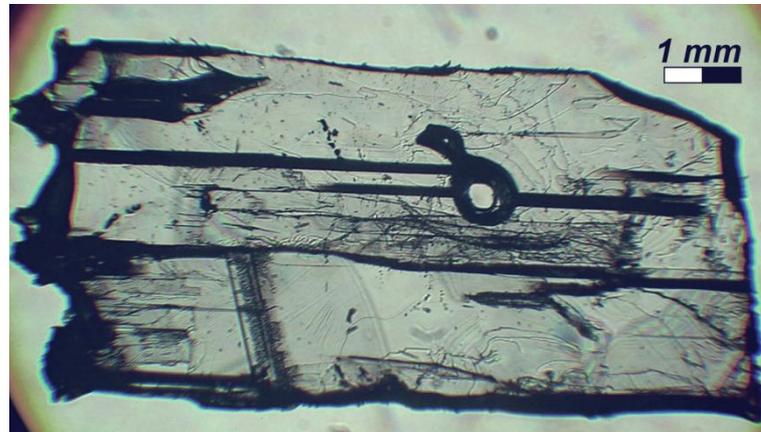


Fig. 1. Single crystal β -Ga₂O₃ plate.

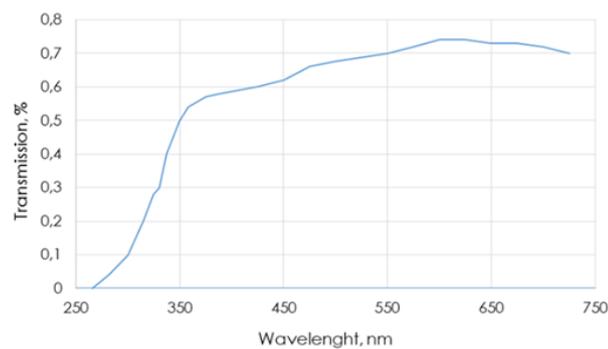


Fig. 2. Optical transmission spectrum of β -Ga₂O₃ crystals.

GaN epitaxial layers on β -Ga₂O₃. The morphology of the GaN films on β -Ga₂O₃ substrates was characterised by electron microscopy (see Fig. 3). The surface of GaN layers is full of three-dimensional features such as faceted pyramids and pits. This is possibly related to non-optimised growth conditions and defects in the β -Ga₂O₃ substrate which were replicated in GaN film.

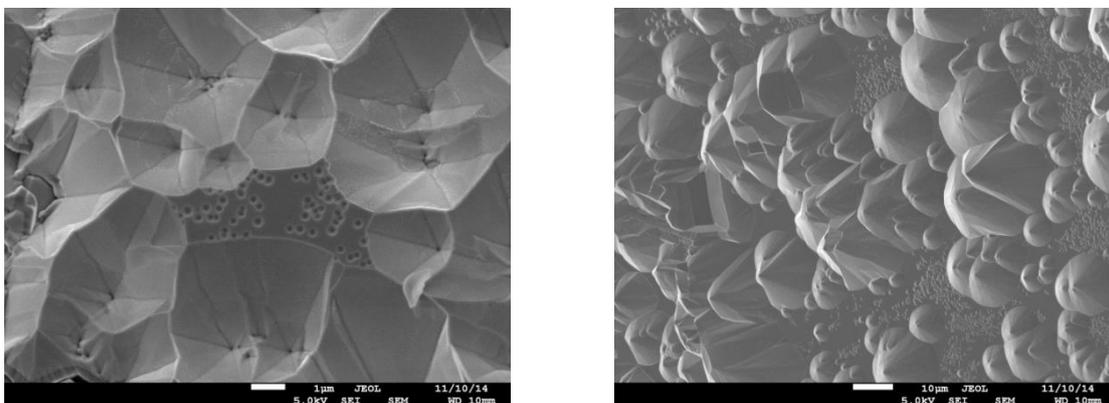


Fig. 3. Plan view SEM image of the HVPE GaN layer on β -Ga₂O₃ single crystal.

Orientation and structural quality of the deposited GaN layers were assessed by means of x-ray diffraction measurements. It was found that the GaN film grows along [0001] direction. Figure 4 shows an omega x-ray diffraction rocking curve of (0002) GaN reflection. The full width at half maximum (FWHM) of the x-ray rocking curve is 546 arcsec. It should be noted that this value is more than twofold larger than typical FWHM values for GaN layers grown on sapphire substrates. Rather broad XRD rocking curve indicates that optimum growth conditions have not been achieved yet.

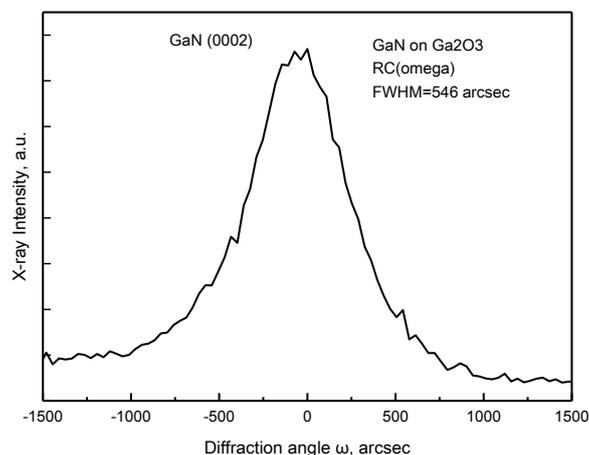


Fig. 4. X-ray diffraction ω -scan of GaN epitaxial film on β -Ga₂O₃ substrate.

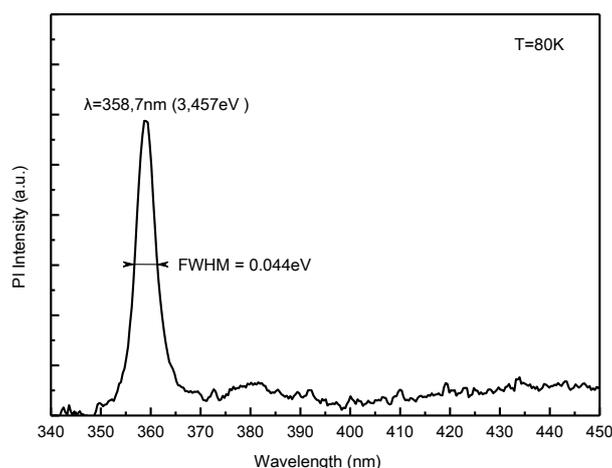


Fig. 5. Low temperature (80K) photoluminescence spectrum of the GaN epitaxial film on β -Ga₂O₃.

Optical quality of the GaN films was analysed by photoluminescence (PL) measurements. PL spectra were obtained at liquid nitrogen temperature (80K) using pulsed nitrogen laser excitation (337 nm). Typical PL spectrum for the GaN film on β -Ga₂O₃ substrate is shown in Figure 5. A strong bandedge emission peak centred at 358.7 nm was observed. A low intensity bump at 385 nm (3.2 eV) is possibly related to donor-acceptor pair recombination. The FWHM of the dominant peak is 44 meV, which is comparable to that for GaN layers grown on sapphire. The intense and narrow band-to-band transition indicates high optical quality of the GaN layer.

4. Conclusions

In conclusion, β -Ga₂O₃ crystals were grown from melt by seedless crystallisation. The crystals were cleaved into (100) platelets which were used as substrates for GaN epitaxial

growth. To the best of our knowledge this is the first report on GaN growth on β -Ga₂O₃ substrates by HVPE technique. Although the quality GaN epitaxial films was somewhat inferior when compared to that of GaN films grown on sapphire under optimised conditions, the initial results provide a compelling proof of concept of β -Ga₂O₃ as a new substrate material for GaN growth.

Acknowledgements

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